



Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10B473KA85PNC
- Description : CAP, 47nF, 25V, ±10%, X7R, 0603
- AEC-Q 200 Specified

A. Samsung Part Number

			<u>CL</u>	<u>10</u>	B	<u>473</u>	K	<u>A</u>	<u>8</u>	<u>5</u>	<u>P</u>	N	<u>C</u>				
			1	2	3	4	5	6	1	8	9	10	1				
1	Series	Samsung Multi-layer Ceramic Capacitor															
2	Size	0603 ((inch c	ode)		L:	1.6	5 ± 0.1	mm			W:		0.8 ± 0.	1 mm	า	
3	Dielectric	X7R					8	Inne	r elec	trode			Ni, (Open mo	de		
4	Capacitance	47 r	nF					Term	ninati	on			Cu,	Ag-epox	у		
5	Capacitance	±10 9	%					Plati	ng				Sn 1	00%	(Pb	Free)	
	tolerance						9	Prod	uct				Auto	motive			
6	Rated Voltage	25 \	V				10	Grad	le coo	le			Stan	dard			
\bigcirc	Thickness	0.8 ±	± 0.1	mm			1	Pack	aging)			Carc	lboard Ty	/pe, 7"	reel	

B. Reliablility Test and Judgement condition

	Performance	Test condition					
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C					
Exposure	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion					
	Tan δ: 0.03 max						
	IR : More than 10,000M Ω or 500M Ω × μ F						
	Whichever is Smaller						
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles					
	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion					
	Tan δ: 0.03 max	1 cycle condition :					
	IR : More than 10,000 or 500 M × μ F	-55+0/-3℃(15±3min) -> Room Temp(1min.)					
	Whichever is Smaller	-> 125+3/-0℃(15±3min) -> Room Temp(1min.)					
Destructive Physical	No Defects or abnormalities	Per EIA 469					
Analysis							
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle					
	Capacitance Change : Within ±12.5%	Heat (25~65 $^\circ C$) and humidity (80~98%), Unpowered					
	Tan δ: 0.03 max	measurement at 24±2hrs after test conclusion					
	IR : More than 10,000M Ω or 500M Ω × μ F						
	Whichever is Smaller						
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85℃/85%RH, Rated Voltate and 1.3~1.5V,					
	Capacitance Change : Within ±12.5%	Add 100kohm resistor					
	Tan δ: 0.035 max	Measurement at 24±2hrs after test conclusion					
	IR : More than 500M Ω or 25M $\Omega \times \mu F$	The charge/discharge current is less than 50mA.					
	Whichever is Smaller						
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,					
Operating Life	Capacitance Change : Within ±12.5%	Measurement at 24±2hrs after test conclusion					
	Tan δ: 0.035 max	The charge/discharge current is less than 50mA.					
	IR : More than 1000M Ω or 50M $\Omega \times \mu$ F						
	Whichever is Smaller						

	Performance	Test condition
External Visual	No abnormal exterior appearance	Microscope ('10)
Physical Dimensions	Within the specified dimensions	Using The calipers
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along
Mechanical Shock	Capacitance Change : Within ±10%	3 mutually perpendicular axes of the test specimen (18 shocks)
	Tan δ , IR : initial spec.	Peakvalue Duration Wave Velocity
		1,500G 0.5ms Half sine 4.7m/sec.
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,
	Capacitance Change : Within ±10%	Use 8"×5" PCB 0.031" Thick 7 secure points on one long side
	Tan δ, IR : initial spec.	and 2 secure points at corners of opposite sides. Parts mounted
		within 2" from any secure point. Test from 10~2000Hz.
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5℃, 10±1sec.
Solder Heat	Capacitance Change : Within ±10%	
	Tan δ, IR : initial spec.	
Thermal Shock	Appearance : No abnormal exterior appearance	-55℃/+125℃.
Thermal onock	Capacitance Change : Within ±10%	Note: Number of cycles required-300,
	Tan δ , IR : initial spec.	Maximum transfer time-20 sec, Dwell time-15min. Air-Air
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002
	Capacitance Change : Within ±10%	
	Tan δ, IR : initial spec.	
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 $^\circ$ for 4 hours, Immerse in solder for 5s at 245±5 $^\circ$
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5°C
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5℃
		solder : a solution ethanol and rosin
Electrical	Capacitance : Within specified tolerance	The Capacitance /D.F. should be measured at 25℃,
Characterization	Tan δ (DF)0.025 max.	1₩z±10%, 1.0±0.2Vrms
	IR(25℃) : More than 10,000№ or 500№× <i>μ</i> F	I.R. should be measured with a DC voltage not exceeding
	IR(125 °C) : More than1,000№ or 10№× μ F	Rated Voltage @25°C, @125°C for 60~120 sec.
	Whichever is Smaller	
	Dielectric Strength	Dielectric Strength : 250% of the rated voltage for 1~5 seconds
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (2mm) for 5 seconds
	Capacitance Change : Within ±10%	
Terminal	Appearance : No abnormal exterior appearance	10N, for 60±1 sec.
Strength(SMD)	Capacitance Change : Within ±10%	
Beam Load	Destruction value should not be exceed	Beam speed
	Chip Length < 2.5mm	0.5±0.05mm/sec
	a) Chip Thickness > 0.5㎜ : 20N	
	b) Chip Thickness \leq 0.5mm : 8N	
Temperature	X7R	
Characterisitcs	(From -55℃ to 125℃, Capacitance change sho	ud be within ±15%)

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ$, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.